

Material Content Data Sheet

RoHS

Sales Product Name	IPD068P03L3 G	**Issued**	29. August 2013
MA#	MA000511346		
Package	PG-TO252-3-311	**Weight***	314.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.479	0.79	0.79	7890	7890
leadframe	non noble metal	iron	7439-89-6	0.162	0.05		517	
	inorganic material	phosphorus	7723-14-0	0.049	0.02		155	
	non noble metal	copper	7440-50-8	162.275	51.63	51.70	516469	517141
wire	non noble metal	aluminium	7429-90-5	2.561	0.82	0.82	8151	8151
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.968	0.63		6264	
	plastics	brominated resin	-	2.109	0.67		6712	
	organic material	carbon black	1333-86-4	2.249	0.72		7159	
	plastics	epoxy resin	-	18.979	6.04		60405	
	inorganic material	silicondioxide	60676-86-0	115.283	36.69	44.75	366906	447446
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11903	11903
plating	non noble metal	nickel	7440-02-0	0.086	0.03		275	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	276
solder	noble metal	silver	7440-22-4	0.056	0.02		180	
	non noble metal	tin	7440-31-5	0.045	0.01		144	
	non noble metal	lead	7439-92-1	2.158	0.69	0.72	6869	7193
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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